

# Highly Versatile Buck-Boost Ambient Energy Manager with Source Voltage Level Configuration

#### **Feature**

#### Ultra-low power start-up

- Cold start from 275 mV input voltage and 3  $\mu$ W input power (typical).

#### Constant input voltage regulation

- Optimized for intermittent and pulse power.
- Selectable operating input voltage from 140 mV to 4.5 V

#### Adaptive and smart energy management

- DCDC switches automatically between boost, buckboost and buck operation, according to input and output voltages, to maximize energy transfer.
- DCDC automatically handles multiple inputs and outputs:
  - Keeps the internal supply and the load voltages regulated while storing the excess of energy in the storage element.
  - The storage element can be used as an input to keep the load and internal voltages regulated when no energy is available on the source.

#### Load supply voltage

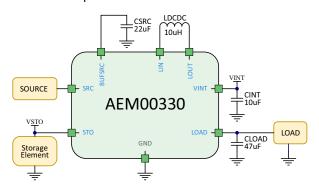
- Selectable load voltage from 1.2 V to 3.3 V.
- Current drive capability: 30 mA in low power mode, 60 mA in high power mode.

#### Battery protection features

- Selectable over-charge and over-discharge protection for any type of rechargeable battery or (super-)capacitor.
- Fast super-capacitor charging.
- Dual cell super-capacitor balancing circuit.

#### Smallest footprint, smallest BOM

- Only four external components are required.
- One 10 μH inductor.
- Three capacitors: one 10  $\mu F,$  one 22  $\mu F$  and one at least 40  $\mu F.$



### Description

The AEM00330 is an integrated energy management circuit that extracts DC power from an ambient energy harvesting source to simultaneously supply an application and store energy in a storage element. The AEM00330 allows to extend battery lifetime and ultimately eliminates the primary energy storage element in a large range of applications.

At start-up, user can choose between charging the storage element first to accumulate energy before the application circuit starts, or charge the load decouplinwg capacitor first to start the application circuit faster.

Thanks to its selectable operating input voltage, it is possible to set a voltage at which the AEM00330 operates. This voltage is between 140 mV and 4.5 V.

With its unique cold start circuit, the AEM00330 can start harvesting with an input voltage as low as 275 mV and from an input power of 3  $\mu$ W. The preset protection levels determine the storage element voltages protection thresholds to avoid over-charging and over-discharging the storage element and thus avoiding damaging it. Those are set through configuration pins. Moreover, custom threshold voltages can be obtained at the expense of a few configuration resistors.

The load voltage can be selected to cover most application needs, with a maximum available load current of 60 mA.

The chip integrates all active elements for powering a typical wireless sensor. Only three capacitors and one inductor are required

# **Applications**

Door access systems	Smart wearable sensors
Smart switches home/building	Point-of-sales (POS)

#### **Device Information**

Part Number	Package	Body size [mm]
10AEM00330J0000	QFN 40-pin	5x5mm

#### **Evaluation Board**

Part Number
2AAEM00330J001



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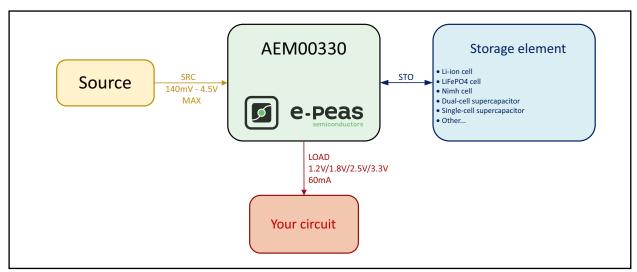


Figure 1: Simplified Schematic View

#### 1. Introduction

The AEM00330 is a full-featured energy efficient power management circuit able to harvest energy from an energy source (connected to SRC) to supply an application circuit (connected to LOAD) and use any excess of energy to charge a storage element (connected to STO). This is done with a minimal bill of material: only 3 capacitors and one inductor are needed for a basic setup.

The heart of the AEM00330 is a regulated switching DCDC converter with high power conversion efficiency.

At first start-up, as soon as a required cold-start voltage of 275 mV and a sparse amount of power of at least 3  $\mu$ W is available at the source, the AEM00330 coldstarts. After the cold start, the AEM extracts the power available from the source if the working input voltage is higher than  $V_{SRC,REG}$ .

Through four configuration pins (STO\_CFG[3:0]), the user can select a specific operating mode out of 15 modes that cover most application requirements without any dedicated external component. Those operating modes define the protection levels of the storage element. If none of those 15 modes fit the user's storage element, a custom mode is also available to allow the user to define a mode with custom specifications.

Status pins ST\_STO, ST\_STO\_RDY and ST\_STO\_OVDIS provide information about the voltage levels of the storage element. ST\_STO is HIGH when the voltage of the storage element  $V_{STO}$  is above  $V_{CHRDY}$  and is reset when the voltage drops below  $V_{OVDIS}$ . ST\_STO\_RDY is HIGH when  $V_{STO}$  is above  $V_{CHRDY}$ , and reset when  $V_{STO}$  drops below  $V_{CHRDY}$ . ST\_STO\_OVDIS is HIGH when  $V_{STO}$  drops below  $V_{OVDIS}$  and reset when  $V_{STO}$  is above  $V_{OVDIS}$ . Status pin ST\_LOAD is HIGH when the load voltage  $V_{LOAD}$  rises above  $V_{LOAD,TYP}$ , and is reset when  $V_{LOAD,MIN}$ .

Depending on the harvester and the application, the source regulation voltage, V<sub>SRC,REG</sub>, can be configured thanks to six configuration pins (SRC\_LVL\_CFG[5:0]).

Once started, if at any time the load requires more power than can be harvested from the energy source, the AEM00330 automatically uses the storage element to keep the load supplied.

The AEM00330's DCDC converter can work in two modes: LOW POWER MODE and HIGH POWER MODE, each one of these being optimized for a power range on SRC and LOAD.

The charging of the storage element can be prevented by pulling EN\_STO\_CH to GND, typically to protect the storage element if the temperature is too low/high to safely charge it.

The AEM00330 also implements a SLEEP STATE, which reduces the quiescent current to avoid wasting the energy stored on the storage element when EN\_SLEEP is HIGH.

At start-up, user can choose to prioritize starting the application circuit connected on LOAD, or charging the storage element connected on STO. This is set by the STO\_PRIO pin.



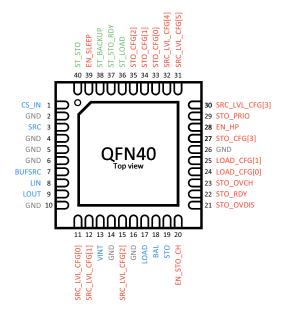


Figure 2: Pinout Diagram QFN 40-pin

NAME	PIN NUMBER	FUNCTIO	N		
Power Pins					
CS_IN	1	Input for	the etern	al cold start circuit.	
SRC	3	Connecti	on to the l	harvested energy source.	
BUFSRC	7	Connecti	on to an e	xternal capacitor buffering the DCDC converter input.	
LIN	8	DCDC ind	uctance c	onnection.	
LOUT	9	DCDC ind	uctance c	onnection.	
VINT	13	Internal v	oltage su	pply.	
LOAD	17	Output v	oltage to s	supply on application load.	
BAL	18		Connection to mid-point of a dual-cell supercapacitor (optional).  Must be connected to GND if not used.		
STO	19	Connection to the energy storage element - battery or (super-)capacitor. Cannot be left floating. Must be connected to a minimum capacitance of $100  \mu F$ or to a rechargeable battery.			
Status Pins					
ST_LOAD	36	Logic Output	HIGH: V <sub>LOAD</sub>	HIGH when the LOAD voltage $V_{LOAD}$ rises above the $V_{LOAD,TYP}$ threshold. LOW when $V_{LOAD}$ drops below $V_{LOAD,MIN}$ threshold.	
ST_STO_RDY	37	Logic Output	HIGH: V <sub>LOAD</sub>	HIGH when $V_{STO}$ is above $V_{CHRDY}$ . LOW when $V_{STO}$ drops below $V_{CHRDY}$ .	
ST_STO_OVDIS	38	Logic Output	HIGH: V <sub>LOAD</sub>	HIGH when the AEM00330 state is SHUTDOWN STATE. LOW when in any other state.	
ST_STO	40	Logic Output	HIGH: V <sub>LOAD</sub>	HIGH when the storage device voltage V <sub>STO</sub> rises above V <sub>CHRDY</sub> threshold.  LOW when V <sub>STO</sub> drops below the V <sub>OVDIS</sub> threshold.	

Table 1: Power and Status Pins





NAME	PIN NUMBER	HIGH LEVEL	FLOATING STATE	FUNCTION			
Configuration Pins							
SRC_LVL_CFG[0]	11						
SRC_LVL_CFG[1]	12						
SRC_LVL_CFG[2]	15		HIGH	Used for the configuration of the source voltage level.			
SRC_LVL_CFG[3]	30	V <sub>VINT</sub>	пібп	Read as HIGH when left floating.			
SRC_LVL_CFG[4]	32						
SRC_LVL_CFG[5]	31						
LOAD_CFG[0]	24	V	IIICII	Used for the configuration of LOAD output voltage V <sub>LOAD</sub> .			
LOAD_CFG[1]	25	V <sub>VINT</sub>	HIGH	Read as HIGH when left floating.			
STO_CFG[0]	33						
STO_CFG[1]	34		HIGH	Used for the configuration of the threshold voltages for the energy storage element V <sub>OVDIS</sub> , V <sub>CHRDY</sub> and V <sub>OVCH</sub> .  Read as HIGH when left floating.			
STO_CFG[2]	35	V <sub>VINT</sub>	пібп				
STO_CFG[3]	27						
STO_PRIO	29	V <sub>VINT</sub>	HIGH	<ul> <li>Pulled up to VINT or floating: storage device (STO) has highest priority at start-up</li> <li>Pulled down to GND: load (LOAD) has highest priority at start-up</li> </ul>			
STO_OVCH	23						
STO_RDY	22			Ition of the threshold voltages ( $V_{OVDIS}$ , $V_{CHRDY}$ and $V_{OVCH}$ ) for the energy storage element re set to custom mode (optional). Must be left floating if not used.			
STO_OVDIS	21	Wileiisi	O_C( O[5.0] al	e set to custom mode (optional). Must be left hoating if not used.			
EN_SLEEP	39	V <sub>LOAD</sub>	Cannot be left floating	<ul> <li>Pulled up to LOAD: SLEEP STATE enabled</li> <li>Pulled down to GND: SLEEP STATE disabled</li> </ul>			
EN_STO_CH	20	V <sub>LOAD</sub>	HIGH	<ul> <li>Pulled up to LOAD or floating: enables the charging of the battery</li> <li>Pulled down to GND: disables the charging of the battery</li> </ul>			
EN_HP	28	V <sub>VINT</sub>	HIGH	<ul> <li>Pulled up to VINTor floating: HIGH POWER MODE enabled</li> <li>Pulled down to GND: HIGH POWER MODE disabled</li> </ul>			
Other							
GND	2, 4, 5, 6, 10, 14, 16, 26	Ground connection, best possible connection to PCB ground plane.					
	Exposed pad						

Table 2: Configuration and Ground Pins



# 2. Absolute Maximum Ratings

#### Parameter Value Voltage on LOAD, STO, SRC, BUFSRC, LIN, -0.3 V to 5.5 V LOUT, BAL, CS\_IN, EN\_SLEEP, EN\_STO\_CH Voltage on VINT, SRC\_LVL\_CFG[5:0], LOAD\_CFG[1:0], STO\_CFG[3:0], STO\_PRIO, -0.3 V to 2.75 V STO\_OVCH, STO\_OVDIS, STO\_RDY, EN\_HP Operating junction temperature -40 °C to 125 °C -65 °C to 150 °C Storage temperature ESD HBM voltage > 2000 V ESD CDM voltage > 500 V

# 3. Thermal Resistance

Package	θЈА	θЈС	Unit
QFN 40-	TBD	TBD	°C/W
pin	100	100	

Table 4: Thermal Resistance

Table 3: Absolute Maximum Ratings

#### **ESD CAUTION**



ESD (ELECTROSTATIC DISCHARGE) SENSITIVE DEVICE

These devices have limited built-in ESD protection and damage may thus occur on devices subjected to high-energy ESD. Therefore, proper EESD precautions should be taken to avoid performance degradation or loss of functionality



# 4. Typical Electrical Characteristics at 25 °C

Symbol	Parameter	Min	Тур	Max	Unit	
Power Conversion	1					
D	Source power required for cold	V <sub>STO</sub> > Vchrdy		3		μW
P <sub>SRC,CS</sub>	start	V <sub>STO</sub> < Vchrdy		6		μW
V	Input valtage of the energy source	During cold start		0.275	4.5	V
V <sub>SRC</sub>	Input voltage of the energy source	After cold start	0.14		4.5	V
V <sub>SRC,REG</sub> V <sub>SRC,REG</sub>	Regulation voltage of the source	See Table 10	Depend	ds on SRC_LVL_( configuration	CFG[5:0]	V
Storage element						
V <sub>OVCH</sub>	Maximum voltage accepted on the storage element before disabling its charging					V
V <sub>CHRDY</sub>	Minimum voltage required on the storage element before asserting the ST_STO	see Table 8	Depends on	V		
V <sub>OVDIS</sub>	Minimum voltage accepted on the storage element before entering into SHUTDOWN STATE					V
Load Output Volta	age					
		V <sub>LOAD</sub> = 1.8V V <sub>STO</sub> > 1.6V HP_EN = 1		60		
I <sub>LOAD,MAX</sub>	LOAD current drive capability	V <sub>LOAD</sub> = 2.5V V <sub>STO</sub> > 1.6V HP_EN = 1		60		mA
		V <sub>LOAD</sub> = 3.3V V <sub>STO</sub> > 1.8V HP_EN = 1		60		
V <sub>LOAD</sub>	Output voltage	see Table 9	Depends on LOAD_CFG[1:0] configuration			V
Internal supply &	Quiescent Current					
V <sub>VINT</sub>	Internal voltage supply			2.2		V
ΙQ	Quiescent current on STO	V <sub>STO</sub> = 3.7V V <sub>LOAD</sub> = 2.5V EN_SLEEP = 0 EN_HP = 0	875			nA
Symbol	Logic Level	LC	)W	HI	GH	
Logic output pins						
ST_STO	Logic output levels on the status STO	GND V <sub>S</sub>			<b>БТО</b>	
ST_LOAD	Logic output levels on the status LOA	GND V <sub>LC</sub>			DAD	
	1	GND V <sub>L0</sub>				
ST_STO_RDY	Logic output levels on the status STO	_READY pin	G	ND	V <sub>L</sub>	DAD

Table 5: Typical Electrical Characteristics



# **5. Recommended Operation Conditions**

Symbol	Parameter	Min	Тур	Max	Unit	
External Components						
L <sub>DCDC</sub>	Inductor of the DCDC converter		10		μН	
C <sub>SRC</sub>	Capacitor decoupling the SRC terminal	13 <sup>1</sup>	22		μF	
C <sub>INT</sub>	Capacitor decoupling the VINT terminal	5 <sup>1</sup>	10		μF	
C <sub>LOAD</sub>	Capacitor decoupling the LOAD terminal	13 <sup>1</sup>	47		μF	
C <sub>STO</sub>	Optional - Capacitor on STO if no storage element is connected (see Section 8.7.1)	, , ,			μF	
STO_OVCH	Configuration of V <sub>OVCH</sub> in custom mode					
STO_OVDIS	Configuration of V <sub>OVDIS</sub> in custom mode 1 Section 8.4		100	МΩ		
STO_RDY	Configuration of V <sub>CHRDY</sub> in custom mode	0.4				
Symbol	Logic Level	LOW		HIGH		
Logic input pins						
LOAD_CFG[1:0]	Configuration pins for the LOAD voltage	GND		VINT		
SRC_LVL_CFG[5:0]	Configuration pins for the SRC voltage level	G	GND		VINT	
STO_CFG[3:0]	Configuration pins for the STO voltage	GND		VINT		
STO_PRIO	Configuration pin for the controller GND		VINT			
EN_STO_FT	Configuration pin for the controller	GND		VINT		
EN_SLEEP	Configuration pin for the controller	GND		LO	AD	
EN_STO_CH	Configuration pin for the controller	GND		LOAD		
EN_HP	Configuration pin for the controller	GND		VINT		

Table 6: Recommended Operation Conditions

<sup>1.</sup> Consider all component tolerance and deratings. Typically, DC-bias derating has a major impact on capacitance on ceramic capacitors.



# 6. Functional Block Diagram

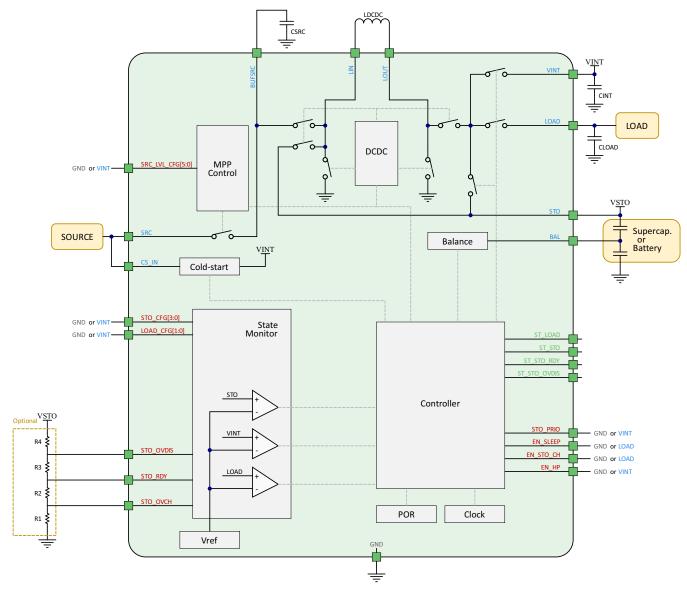


Figure 3: Functional Block Diagram



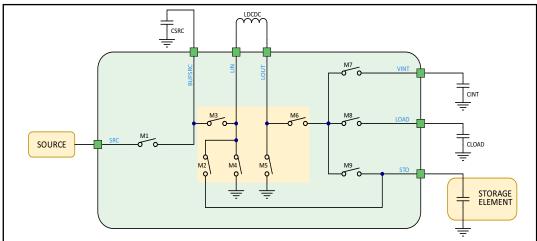


Figure 4: Simplified Schematic View of the AEM00330

### 7. Theory of Operation

#### 7.1. DCDC Converter

The DCDC converter converts the voltage available at BUFSRC or at STO to a level suitable for charging the storage element STO or to regulate the LOAD and the internal supply VINT. The switching transistors of the DCDC converter are M2 or M3, M4, M5 and M6. Thanks to M7, M8 and M9, the controller selects between LOAD, STO and VINT respectively as the converter output. M1 selects the source as main input of energy. The internal supply VINT is regulated with priority over LOAD. STO is selected as an output only when neither VINT nor LOAD needs to be supplied. The converter has two possible inputs: BUFSRC or STO. BUFSRC is used by default as an input via M3. If the energy available on SRC is not sufficient to maintain the LOAD or VINT voltage, for instance because of a sudden current peak on LOAD, the converter uses STO instead as an input via M2 to keep LOAD and VINT regulated.

The reactive power component of this converter is the external inductor  $L_{DCDC}$ .  $V_{SRC}$  is regulated to  $V_{SRC,REG}$  configured by  $SRC\_LVL\_CFG[5:0]$ . BUFSRC is decoupled by the capacitor  $C_{SRC}$ , which smooths the voltage against the current pulses pulled by the DCDC converter. The storage element is connected to the STO pin.

Depending on its input voltage and its output voltage, the DCDC converter will work as a boost converter, a buck converter or a buck-boost converter. The maximum power that can be harvested and supplied to the output LOAD depends on the power mode (HIGH POWER MODE or LOW POWER MODE), which is configured through the EN\_HP pin (see Section 8.1).

DCDC Converter Mode	Input Voltage / Output Voltage
Boost	<b>V<sub>IN</sub> &lt; V<sub>OUT</sub> -</b> 250 mV
Buck	<b>V<sub>IN</sub> &gt; V<sub>OUT</sub> +</b> 250 mV
Buck - Boost	<b>V<sub>OUT</sub></b> - 250 mV < <b>V<sub>IN</sub></b> < <b>V<sub>OUT</sub></b> + 250 mV

Table 7: DCDC Converter Modes

#### 7.2. Cold-Start Circuit

The AEM00330 is able to coldstart if the voltage on CS\_IN is above 0.275 V. The minimum available power is:

- $3 \mu W$  if  $V_{STO}$  is above  $V_{CHRDY}$ .
- $6 \mu W$  if  $V_{STO}$  is below  $V_{CHRDY}$ .

CS\_IN is typically connected to SRC to allow the AEM00330 to coldstart from the energy available on the harvester. Nevertheless, any other energy source can be connected to CS\_IN as long as it meets the electrical specifications constraints described in Sections 4 and 5.



#### 7.3. AEM00330 States Description

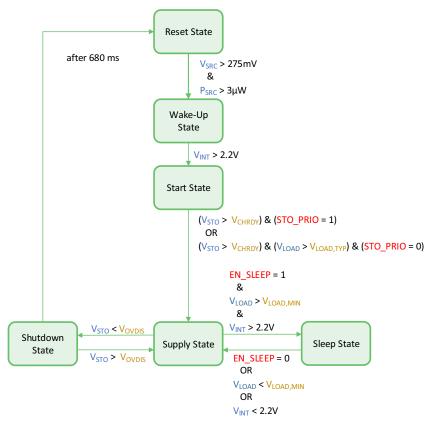


Figure 5: Diagram of the AEM00330 States

#### 7.3.1. Reset, Wake Up and Start States

The RESET STATE is a state where all nodes are deeply discharged and there is no available energy to be harvested. As soon as the required cold start voltage of 275 mV and a sparse amount of power of just 3 µW become available on CS\_IN (usually connected to SRC), the AEM00330 switches to WAKE-UP STATE, and energy is extracted from SRC to make V<sub>VINT</sub> rise to 2.2 V. When V<sub>VINT</sub> reaches those 2.2 V, the AEM00330 switches to START STATE. In START STATE, two scenarios are possible: in the first scenario, STO\_PRIO is HIGH, the storage element connected to STO has the priority on the one connected to LOAD. In the second scenario, STO\_PRIO is reset and the LOAD has the priority.

When the AEM00330 is in RESET STATE, WAKE-UP STATE or START STATE, the DCDC converter's input is always BUFSRC: STO is never used as input. This guarantees that the storage element is not used until a minimum amount of energy has been stored in it.

#### 7.3.1.1. Storage Element Priority

This paragraph covers the AEM00330 behavior when STO\_PRIO is pulled up to VINT, so that the storage element connected on STO has priority over LOAD.

#### **Supercapacitor as a Storage Element**

If the storage element is a supercapacitor, it may be fully discharged at first and thus need to be charged from 0 V. The DCDC converter charges STO from the input source (SRC). When  $V_{STO}$  reaches  $V_{CHRDY}$ , the circuit enters SUPPLY STATE.

#### **Battery as a Storage Element**

If the storage element is a battery, but its voltage is lower than  $V_{CHRDY}$ , then the storage element needs to be charged first until it reaches  $V_{CHRDY}$ . Once  $V_{STO}$  reaches  $V_{CHRDY}$ , or if the battery was initially charged above  $V_{CHRDY}$ , the circuit enters SUPPLY STATE.



#### 7.3.1.2. Load Priority

If STO\_PRIO is connected to GND, the AEM charges first the LOAD to V<sub>LOAD,MAX</sub> (see Table 9) using energy from the source (SRC). This allows to first supply the application circuit connected to LOAD. If the storage element was initially charged above V<sub>CHRDY</sub>, the circuit enters SUPPLY STATE as soon as LOAD reaches V<sub>LOAD,TYP</sub>. If the storage element is a supercapacitor or a battery which voltage is lower than V<sub>CHRDY</sub>, the AEM keeps regulating LOAD between V<sub>LOAD,MAX</sub> and V<sub>LOAD,TYP</sub>. Meanwhile, any excess charges on the source is used to charge the storage element until it reaches V<sub>CHRDY</sub>. Once V<sub>STO</sub> exceeds V<sub>CHRDY</sub>, the circuit enters into SUPPLY STATE.

This configuration is useful when a large storage element is connected to STO and a smaller one is connected to LOAD: the application starts as soon as  $C_{LOAD}$  is charged and does not have to wait for the large storage element on STO to be charged.

#### 7.3.2. Supply State

In **SUPPLY STATE**, four scenarios are possible:

- There is enough power provided by the source (SRC) to keep V<sub>LOAD</sub> near V<sub>LOAD,TYP</sub> with a small hysteresis and V<sub>VINT</sub> at 2.2 V. The excessive power is used to charge the storage element on STO. In that case, the circuit remains in SUPPLY STATE. If STO is fully charged, LOAD will be maintained at V<sub>LOAD,MAX</sub> instead of V<sub>LOAD,TYP</sub>. If all nodes are fully charged, the DCDC converter is disabled to prevent over-charging the storage element, and the SRC pin is set to high impedance.
- If the circuit connected to LOAD consumes more energy than the energy that the AEM00330 is able to extract from the source, the LOAD circuit will be supplied by the storage element connected to the STO terminal. In this case, the circuit stays in SUPPLY STATE.
- Due to a lack of power from the source, V<sub>STO</sub> falls below V<sub>OVDIS</sub>. In this case, the circuit enters SHUTDOWN STATE as explained in Section 7.3.3.
- If EN\_SLEEP is HIGH and conditions (shown on Figure 5) on V<sub>LOAD</sub> and V<sub>VINT</sub> are satisfied, the AEM enters SLEEP STATE (see section 7.3.4).

#### 7.3.3. Shutdown State

If the storage element gets depleted ( $V_{STO} < V_{OVDIS}$ ), the AEM00330 goes to SHUTDOWN STATE. As long as the AEM00330 is in this state, the ST\_STO\_OVDIS is HIGH. In SHUTDOWN STATE, if  $V_{STO}$  recovers within 680 ms, the AEM00330 goes back to SUPPLY STATE. This prevents false detection of the storage element being empty because of a LOAD current peak.

#### 7.3.4. Sleep State

SLEEP STATE reduces the AEM00330 guiescent current by disabling the DCDC converter and by reducing the controller clock frequency. If V<sub>VINT</sub> or V<sub>LOAD</sub> fall below their regulation value, the AEM00330 temporarily exits SLEEP STATE to wake up the DCDC converter and supply VINT or LOAD. Exiting SLEEP STATE and waking up the DCDC converter takes up to 1 ms. Depending on the expected LOAD current, CLOAD value must be adapted to act as an energy buffer during the 1 ms required to wake up the DCDC converter. Therefore, this state may be enabled when LOAD current is small, and be disabled if a high LOAD current is expected. As the DCDC is disabled, no energy is harvested from SRC while in SLEEP STATE, so that the storage element connected to STO is no longer charged. LOAD and VINT are the only nodes that are still supplied and regulated when the AEM00330 is in SLEEP STATE. This mode is useful to limit the current drawn on STO when the application circuit has detected that the power available on SRC is so low that it wouldn't compensate the AEM00330 internal circuit power consumption (see Table 5).

The AEM00330 enters SLEEP STATE if all the following conditions are satisfied:

- EN\_SLEEP pin pulled up to LOAD
- $V_{VINT} > 2.2 V$
- V<sub>LOAD</sub> > V<sub>LOAD,TYP</sub>

The AEM00330 leaves SLEEP STATE and switches back to SUPPLY STATE if one of the following conditions is satisfied:

- EN\_SLEEP pin pulled down to GND
- V<sub>VINT</sub> < 2.2 V
- V<sub>LOAD</sub> < V<sub>LOAD.TYP</sub>

The AEM00330 will then stay in SUPPLY STATE until the SLEEP STATE conditions are all satisfied again.



#### 7.4. Source Voltage Regulation

During SUPPLY STATE, the voltage on SRC is regulated to a voltage configured by the user. The AEM00330 offers a choice of fifty-nine values for the source voltage. If the open-circuit voltage of the harvester is lower than  $V_{SRC,REG}$ , the AEM00330 does not extract the power from the source. If the SRC voltage is higher, the AEM00330 regulates  $V_{SRC}$  to  $V_{SRC,REG}$  and extracts power.

#### 7.5. Balancing for Dual-Cell Supercapacitor

The balancing circuit allows the user to balance the internal voltage of the dual-cell supercapacitor connected to STO in order to avoid damaging the supercapacitor because of excessive voltage on one cell.

If BAL is connected to GND, the balancing circuit is disabled. This configuration must be used if a battery, a capacitor or a single-cell supercapacitor is connected on STO.

If BAL is connected to the node between both cells of a supercapacitor, the balancing circuit compensates for any mismatch of the two cells that could lead to the over-charge of one of two cells. The balancing circuit ensures that BAL remains close to V<sub>STO</sub> / 2. This configuration must be used if a dual-cell supercapacitor is connected to STO, and that this supercapacitor requires cells balancing.

The balancing circuit works as follows, with  $V_{\text{BAL}}$  the voltage on the BAL pin:

- $V_{BAL} > \frac{V_{STO}}{2}$ : the AEM00330 enables a switch between BAL and GND to discharge the bottom supercapacitor cell to GND (up to 20 mA).
- $V_{BAL} < \frac{V_{STO}}{2}$ : the AEM00330 enables a switch between STO and BAL to discharge the top supercapacitor cell to the bottom supercapacitor cell (up to 20 mA).

NOTE: the balancing feature is optimized for supercapacitors, for use with other storage elements (batteries, etc.), please contact e-peas support.



# 8. System Configuration

### 8.1. High Power / Low Power Mode

When EN\_HP is pulled to VINT, the DCDC converter is configured to HIGH POWER MODE. This allows higher currents to be extracted from the DCDC converter input (SRC or STO) to the DCDC converter output (LOAD or STO). Figure 6 shows the maximum current that the DCDC converter can supply to LOAD, depending on the storage voltage V<sub>STO</sub>, for every available load voltage V<sub>LOAD</sub>, for both HIGH POWER MODE and LOW POWER MODE.

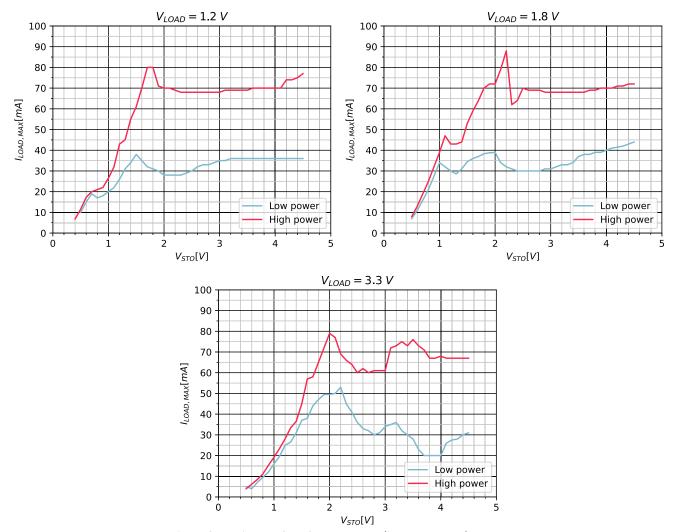


Figure 6: Maximum LOAD Current Depending on  $V_{STO}$  and on  $V_{LOAD}$ 

#### 8.2. Storage Element Configuration

Through four configuration pins (STO\_CFG[3:0]), the user can set a particular operating mode from a range that covers most application requirements, without any dedicated external component as shown in Table 8. The three threshold levels are defined as:

- V<sub>OVCH</sub>: maximum voltage accepted on the storage element before disabling its charging.
- V<sub>CHRDY</sub>: minimum voltage required on the storage element before starting to supply the LOAD (if STO\_PRIO is HIGH) and entering supply state after start-up.



 V<sub>OVDIS</sub>: minimum voltage accepted on the storage element before considering the storage element as depleted, thus setting ST\_STO LOW.

A large-size storage element is not mandatory on STO:

- If the harvested energy source is permanently available and covers the application needs or

 If the application does not need to store energy when the harvested energy source is not available

The storage element may then be replaced by an external capacitor  $C_{STO}$  with a minimum value of 100  $\mu F.\,$ 

Caution: running the AEM00330 without this 100  $\mu\text{F}$  minimum capacitance on STO will permanently damage the circuit.

Cor	nfigura	ation p	oins	Storage element threshold voltages			Typical use	
S	STO_CFG[3:0]			V <sub>OVDIS</sub>	V <sub>CHRDY</sub>	V <sub>OVCH</sub>		
0			4.05 V	LiCoO <sub>2</sub> battery, Li-Po battery, Lithium Titanate (3.8 V) battery (long life).				
0	0	0	1	2.80 V	3.10 V	3.60 V	LiFePO <sub>4</sub> battery, Lithium capacitor (LiC).	
0	0	1	0	1.85 V	2.40 V	2.70 V	Dual-cell NiMH battery, Lithium-Titanate (2.4V) battery.	
0	0	1	1	0.20 V 1.00 V 4.65 V		4.65 V	Dual-cell supercapacitor.	
0	1	0	0	0.20 V 1.00 V 2.60 V		2.60 V	Single-cell supercapacitor.	
0	1	0	1	1.00 V	1.20 V	2.95 V	Single-cell supercapacitor.	
0	1	1	0	1.85 V	2.30 V	2.60 V	Lithium-Titanate battery (2.4V).	
0	1	1	1	Cu			ustom Mode (single-cell NiMH battery, LiC, etc.) <sup>1</sup> .	
1	0	0	0	1.10 V	1.25 V	1.50 V	Ni-Cd single-cell battery.	
1	0	0	1	2.20 V	2.50 V	3.00 V	Ni-Cd dual-cell battery.	
1	0	1	0	1.45 V	2.00 V	4.65 V	Dual-cell supercapacitor.	
1	0	1	1	1.00 V	1.20 V	2.60 V	Single-cell supercapacitor.	
1	1	0	0	2.00 V	2.30 V	2.60 V	Solid State battery.	
1	1	0	1	3.00 V	3.50 V	4.35 V	LiCoO <sub>2</sub> battery, Li-Po battery, Lithium Titanate (3.8 V) battery.	
1	1	1	0	2.60 V	2.70 V	4.00 V	Tadiran TLI.	
1	1	1	1	2.60 V 3.50 V 3.90 V		3.90 V	Tadiran HLC.	

**Table 8: Storage Element Configuration Pins** 

<sup>1.</sup> An example of a single-cell NiMH batteries optimized custom mode setting can be found at Section 9.2.



### 8.3. Load Configuration

The LOAD output voltage V<sub>LOAD</sub> can be configured thanks to the LOAD\_CFG[1:0] configuration pins covering most application cases (see Table 9).  $V_{\mbox{\scriptsize LOAD}}$  is regulated to  $V_{LOAD,TYP}$ . However, if  $V_{LOAD}$  falls below  $V_{LOAD,MID}$ , the controller forces STO as an input of the DCDC converter to supply LOAD.

When the AEM00330 is in SUPPLY STATE:

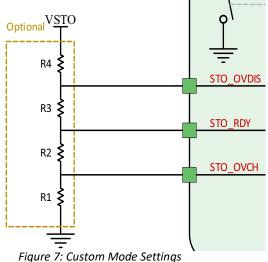
- V<sub>LOAD</sub> < V<sub>LOAD,MID</sub>: the AEM00330 charges C<sub>LOAD</sub> by transferring the energy available on the storage element STO (if V<sub>STO</sub> is above V<sub>OVDIS</sub>), even if energy is available on SRC.
- V<sub>LOAD.MID</sub> < V<sub>LOAD</sub> < V<sub>LOAD.MAX</sub>:
  - If energy is available on SRC, the AEM00330 uses it to charge C<sub>LOAD</sub>.
  - If no energy is available on SRC, the AEM00330 uses the energy available on STO to charge C<sub>LOAD</sub>.

- $V_{\mbox{\scriptsize LOAD},\mbox{\scriptsize TYP}}$  is the typical average voltage to be expected on the LOAD pin.
- $ST_LOAD$  reflects  $V_{LOAD}$ , with an hysteresis between V<sub>LOAD,MIN</sub> and V<sub>LOAD,TYP</sub>:
  - ST\_LOAD is HIGH when  $V_{LOAD} > V_{LOAD TYP}$ .
  - ST\_LOAD is LOW when V<sub>LOAD</sub> < V<sub>LOAD,MIN</sub>.
- As a reminder, the order of priority in which the nodes are recharged is as follows:
  - VINT always has the highest priority, as it is mandatory to keep the AEM00330 internal circuit supplied.
  - LOAD has the second highest priority, to keep the application circuit supplied.
  - STO has the lowest priority, as the storage element is used to store the excessive energy from SRC.

Configura	ation pins	LOAD output voltage				
LOAD_0	CFG[1:0]	V <sub>LOAD,MIN</sub>	V <sub>LOAD,MID</sub>	V <sub>LOAD,TYP</sub>	V <sub>LOAD,MAX</sub>	
0	0	3.15 V	3.23 V	3.28 V	3.34 V	
0	1	2.35 V	2.47 V	2.50 V	2.53 V	
1	0	1.64 V	1.75 V	1.79 V	1.82 V	
1	1	1.14 V	1.16 V	1.20 V	1.23 V	

Table 9: Load Configuration Pins

### 8.4. Custom Mode Configuration



When STO CFG[3:0] = 0111, the custom mode is selected and all four configuration resistors must be wired as shown in Figure 7.

V<sub>OVCH</sub>, V<sub>CHRDY</sub> and, V<sub>OVDIS</sub> are defined thanks to R1, R2, R3 and R4, which can be determined within the following constraints:

$$- R_{T} = R_{1} + R_{2} + R_{3} + R_{4}$$

$$- 1M\Omega \le R_{T} \le 100M\Omega$$

$$- R_1 = R_T \cdot \frac{1V}{V_{OVCH}}$$

$$- R_2 = R_T \cdot \left( \frac{1V}{V_{CHRDY}} - \frac{1V}{V_{OVCH}} \right)$$

$$- R_3 = R_T \cdot \left(\frac{1V}{V_{OVDIS}} - \frac{1V}{V_{CHRDY}}\right)$$

$$- R_4 = R_T \cdot \left(1 - \frac{1V}{V_{OVDIS}}\right)$$

The resistors should have high values to make the additional power consumption negligible. Moreover, the following constraints must be respected to ensure the functionality of the chip:

- 
$$V_{CHRDY} + 0.05V \le V_{OVCH} \le 4.5V$$

- 
$$V_{OVDIS} + 0.05V \le V_{CHRDY} \le V_{OVCH} - 0.05V$$

- 1V ≤ V<sub>OVDIS</sub>



### 8.5. Disable Storage Element Charging

Pulling down EN\_STO\_CH pin to GND disables the charging of the storage element connected to STO from SRC. This can be done for example to protect the storage element when the system detects that the environment temperature is too low or too high to safely charge the storage element.

While EN\_STO\_CH is pulled down, VINT and LOAD can still be supplied either from SRC or from STO.

To enable charging the storage element on STO, EN\_STO\_CH must be pulled up to LOAD or left floating (pin is pulled up internally).

Please note that STO will still be charged to  $V_{\text{CHRDY}}$  during the START STATE



# 8.6. Source Level Configuration

Six dedicated configuration pins, SRC\_LVL\_CFG[5:0], allow selecting the  $V_{SRC,REG}$  at which the source regulates its voltage.

	Voltage Level					
	V <sub>SRC,REG</sub>					
0	0	0	0	0	0	0.14 V
0	0	0	0	0	1	0.17 V
0	0	0	0	1	0	0.20 V
0	0	0	0	1	1	0.23 V
0	0	0	1	0	0	0.26 V
0	0	0	1	0	1	0.30 V
0	0	0	1	1	0	0.34 V
0	0	0	1	1	1	0.39 V
0	0	1	0	0	0	0.43 V
0	0	1	0	0	1	0.48 V
0	0	1	0	1	0	0.52 V
0	0	1	0	1	1	0.57 V
0	0	1	1	0	0	0.61 V
0	0	1	1	0	1	0.66 V
0	0	1	1	1	0	0.70 V
0	0	1	1	1	1	0.75 V
0	1	0	0	0	0	0.80 V
0	1	0	0	0	1	0.84 V
0	1	0	0	1	0	0.89 V
0	1	0	0	1	1	0.95 V
0	1	0	1	0	0	1.05 V
0	1	0	1	0	1	1.14 V
0	1	0	1	1	0	1.23 V
0	1	0	1	1	1	1.32 V
0	1	1	0	0	0	1.41 V
0	1	1	0	0	1	1.50 V
0	1	1	0	1	0	1.59 V
0	1	1	0	1	1	1.68 V
0	1	1	1	0	0	1.77 V
0	1	1	1	0	1	1.86 V

	Voltage Level					
	V <sub>SRC,REG</sub>					
0	1	1	1	1	0	1.95 V
0	1	1	1	1	1	2.05 V
1	0	0	0	0	0	2.14 V
1	0	0	0	0	1	2.23 V
1	0	0	0	1	0	2.32 V
1	0	0	0	1	1	2.41 V
1	0	0	1	0	0	2.50 V
1	0	0	1	0	1	2.59 V
1	0	0	1	1	0	2.68 V
1	0	0	1	1	1	2.77 V
1	0	1	0	0	0	2.86 V
1	0	1	0	0	1	2.95 V
1	0	1	0	1	0	3.05 V
1	0	1	0	1	1	3.14 V
1	0	1	1	0	0	3.23 V
1	0	1	1	0	1	3.32 V
1	0	1	1	1	0	3.41 V
1	0	1	1	1	1	3.50 V
1	1	0	0	0	0	3.59 V
1	1	0	0	0	1	3.68 V
1	1	0	0	1	0	3.77 V
1	1	0	0	1	1	3.86 V
1	1	0	1	0	0	3.95 V
1	1	0	1	0	1	4.05 V
1	1	0	1	1	0	4.14 V
1	1	0	1	1	1	4.23 V
1	1	1	0	0	0	4.32 V
1	1	1	0	0	1	4.41 V
1	1	1	0	1	0	4.50 V

Table 10: Source regulation configuration pins



#### 8.7. External Components

Refer to Figure 17 to have an illustration of the external components wiring.

#### 8.7.1. Storage Element Information

The energy storage element of the AEM00330 can be a rechargeable battery, a supercapacitor or a capacitor. The size of the storage element must be determined so that its voltage does not fall below V<sub>OVDIS</sub> even during current peaks pulled by the application circuit connected to LOAD. If the internal resistance of the storage element cannot sustain this voltage limit, it is advisable to decouple the battery with a capacitor.

If the application expects a disconnection of the battery (e.g. because of a user removable connector), the PCB should include a capacitor  $C_{STO}$  of at least 100  $\mu F$  connected between STO and GND. The leakage current of the storage element should be small as leakage currents directly impact the quiescent current of the whole subsystem.

#### 8.7.2. External Inductor Information

The AEM00330 operates with one standard miniature inductor. L<sub>DCDC</sub> must sustain a peak current of at least 1 A and a switching frequency of at least 10 MHz. Low equivalent series resistance (ESR) favors the power conversion efficiency of the DCDC converter. The recommended value is 10  $\mu\text{H}.$ 

#### 8.7.3. External Capacitors Information

#### 8.7.3.1. C<sub>SRC</sub>

This capacitor acts as an energy buffer at the input of the DCDC converter. It prevents large voltage fluctuations when the DCDC converter is switching. The recommended nominal value is 22  $\mu$ F.

#### 8.7.3.2. C<sub>INT</sub>

This capacitor acts as an energy buffer for the internal voltage supply. The recommended nominal value is 10  $\mu$ F.

#### 8.7.3.3. C<sub>LOAD</sub>

This capacitor acts as an energy buffer for LOAD. It also reduces the voltage ripple induced by the current pulses inherent to the switched behavior of the converter. The recommended value is at least 13  $\mu F$  (considering derating and tolerance).



# 9. Typical Application Circuits

### 9.1. Example Circuit 1

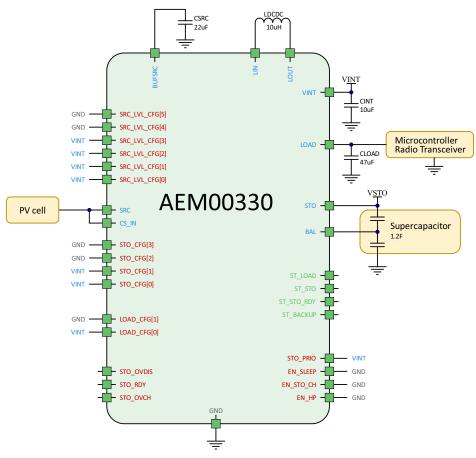


Figure 8: Typical Application Circuit 1

The circuit is an example of a system with solar energy harvesting. It uses a pre-defined operating mode that uses standard components, and a supercapacitor as energy storage.

- Energy source: PV cell
- SRC\_LVL\_CFG[5:0] = 001111: the AEM00330 starts to extract power from 0.75 V and regulates V<sub>SRC</sub> to 0.75 V.
- STO\_CFG[3:0] = 0011: the storage element is a dual-cell supercapacitor, with:
  - V<sub>OVCH</sub> = 4.65 V
  - V<sub>CHRDY</sub> = 1.00 V
  - V<sub>OVDIS</sub> = 0.20 V

- The balancing pin of the dual-cell supercapacitor is connected to BAL
- LOAD\_CFG[1:0] = 01: the microcontroller and the radio transceiver are supplied by the LOAD terminal, which is regulated at V<sub>LOAD</sub> = 2.5 V
- STO\_PRIO is connected to VINT: at start-up STO will be charged and before LOAD
- EN\_SLEEP is connected to GND: the AEM00330 will never switch to SLEEP STATE
- EN\_STO\_CH is connected to GND: the charging of the storage element on STO is disabled
- EN\_HP is connected to GND: the DCDC converter is in LOW POWER MODE



### 9.2. Example Circuit 2

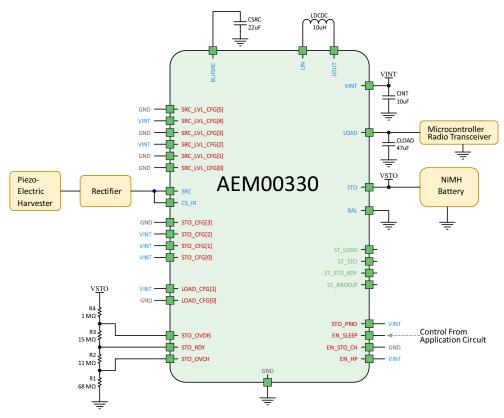


Figure 9: Typical Application Circuit 2

The circuit is an example of a system with vibration energy harvesting. It uses a dual-cell energy storage element made of two NiMH rechargeable batteries. The voltage thresholds are set by the custom mode.

- Energy source: piezoelectric vibration harvester.
- SRC\_LVL\_CFG[5:0] = 010100: the AEM00330 starts to extract power from 1.05V and regulates V<sub>SRC</sub> to 1.05V.
- STO\_CFG[3:0] = 0111: the storage element is a Li-Po rechargeable battery, used with custom mode:
  - V<sub>OVDIS</sub> = 1.00 V
  - V<sub>CHRDY</sub> = 1.20 V
  - V<sub>OVCH</sub> = 1.40 V
- Custom mode resistor divider calculations (values have been chosen to match E24 series value):
  - $R_T = 95M\Omega$
  - $R_1 = R_T \cdot \frac{1V}{V_{OVCH}} \approx 68M\Omega$
  - $R_2 = R_T \cdot \left( \frac{1V}{V_{CHRDY}} \frac{1V}{V_{OVCH}} \right) \approx 11M\Omega$
  - $R_3 = R_T \cdot \left(\frac{1V}{V_{OVDIS}} \frac{1V}{V_{CHRDY}}\right) \approx 15M\Omega$

- 
$$R_4 = R_T \cdot \left(1 - \frac{1V}{V_{OVDIS}}\right) \approx 1M\Omega$$

- BAL is not used (no a dual-cell storage element) so it is connected to GND.
- LOAD\_CFG[1:0] = 10: the micro-controller and the radio transceiver are supplied by the LOAD terminal, which is regulated at V<sub>LOAD</sub> = 1.8V.
- STO\_PRIO is connected to VINT: at start-up STO will be charged and before LOAD.
- EN\_SLEEP is controlled by the application circuit, typically by a microcontroller GPIO output.
- EN\_STO\_CH is connected to LOAD: the charging of the storage element present on STO is enabled.
- EN\_HP is connected to VINT: the DCDC converter is in HIGH POWER MODE

NOTE: for LiC storage elements, or others that would not be covered by STO\_CFG presets, please apply the same equations to determine custom mode resistors values. E24 series values for typical storage elements can be found in the AEM00330 Configuration Tool spreadsheet, to be downloaded on e-peas website.



#### 10. Circuit Behavior

### 10.1. Wake-up state, Start state and Supply state

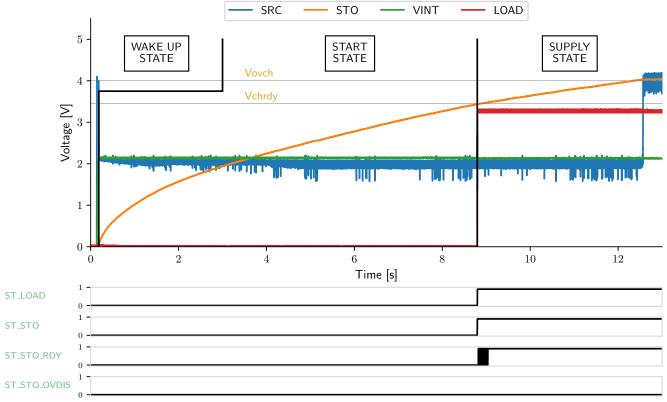


Figure 10: Wake-up state, Start state and Supply state

- STO\_CFG[3:0] = 0000
  - V<sub>OVDIS</sub> = 3.00 V
  - V<sub>CHRDY</sub> = 3.50 V
  - V<sub>OVCH</sub> = 4.05 V
- SRC\_LVL\_CFG[5:0] = 011111 (V<sub>SRC,REG</sub> = 2.05 V)
- C<sub>STO</sub> = 10 mF
- SRC: 5 mA current source with 4 V voltage compliance

- LOAD\_CFG[1:0] = 00 (V<sub>LOAD,TYP</sub> = 3.28 V)
- EN\_HP = 1 (high power mode)
- EN\_STO\_CH = 1 (storage element charge enabled)
- STO\_PRIO = 1 (storage element charged in priority after startup)
- EN\_SLEEP = 0 (sleep mode disabled)



### 10.2. Supply state, Shutdown state and Reset state

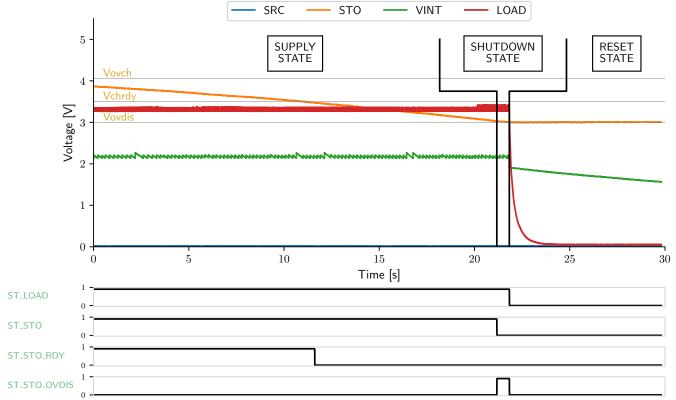


Figure 11: Supply State, Shutdown state and Reset state

- STO\_CFG[3:0] = 0000
  - V<sub>OVDIS</sub> = 3.00 V
  - V<sub>CHRDY</sub> = 3.50 V
  - V<sub>OVCH</sub> = 4.05 V
- LOAD\_CFG[1:0] = 00 (V<sub>LOAD,TYP</sub> = 3.28 V)
- SRC\_LVL\_CFG[5:0] = 011111 (V<sub>SRC.REG</sub> = 2.05 V)
- C<sub>STO</sub> = 10 mF

- SRC: left floating force the storage element on STO to discharge
- EN\_HP = 1 (high power mode)
- STO\_PRIO = 1 (storage element charged in priority after startup)
- EN\_STO\_CH = 1 (storage element charge enabled)
- EN\_SLEEP = 0 (sleep mode disabled)
- 10 kΩ connected between LOAD and GND



#### 11. Performance Data

# 11.1. DCDC Conversion Efficiency From SRC to STO in Low Power Mode

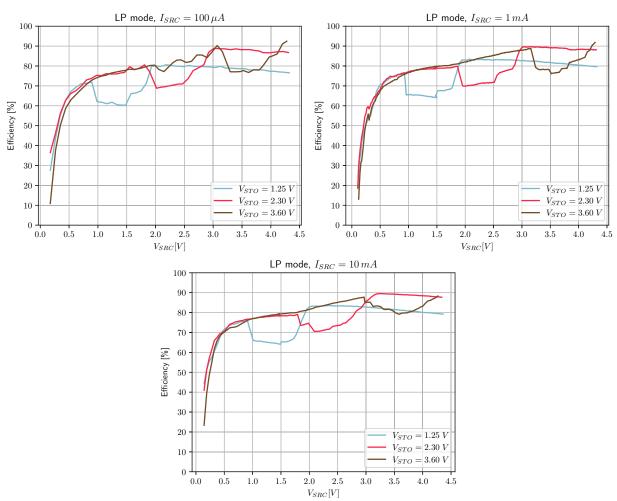


Figure 12: DCDC Efficiency from SRC to STO for 1 mA and 10 mA in Low Power Mode

# 11.2. DCDC Conversion Efficiency From SRC to STO in High Power Mode

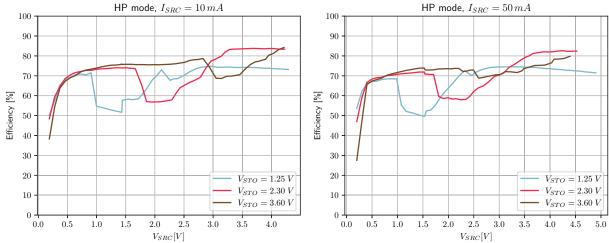


Figure 13: DCDC Efficiency from SRC to STO for 10 mA and 50 mA in High Power Mode



# 11.3. DCDC Conversion Efficiency From STO to LOAD in Low Power Mode

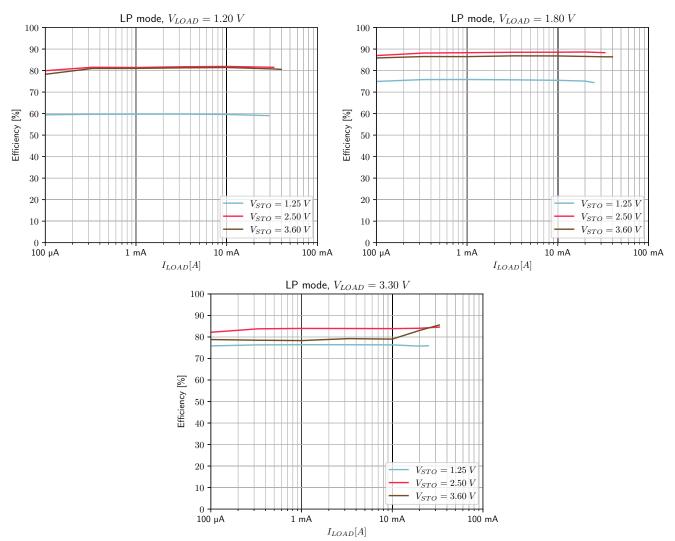


Figure 14: DCDC Efficiency from STO to LOAD in Low Power Mode



# 11.4. DCDC Conversion Efficiency From STO to LOAD in High Power Mode

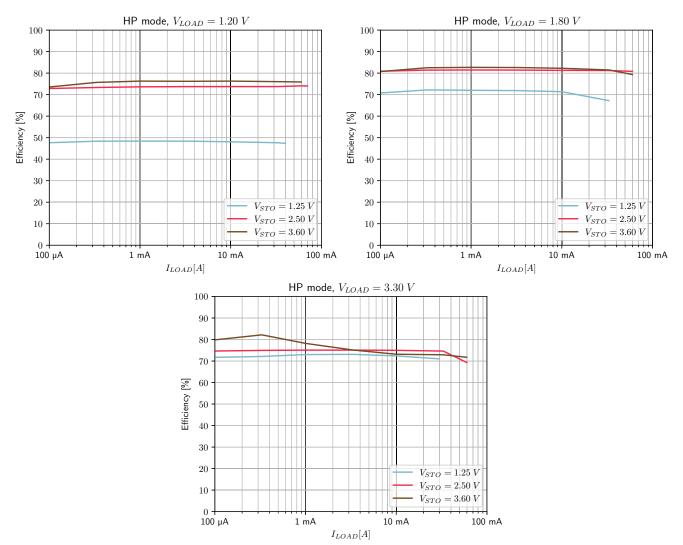


Figure 15: DCDC Efficiency from STO to LOAD in High Power Mode



# 11.5. Quiescent Current

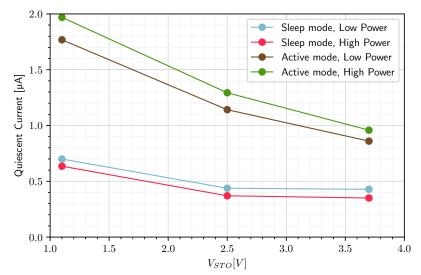


Figure 16: Quiescent Current



# 12. Schematic

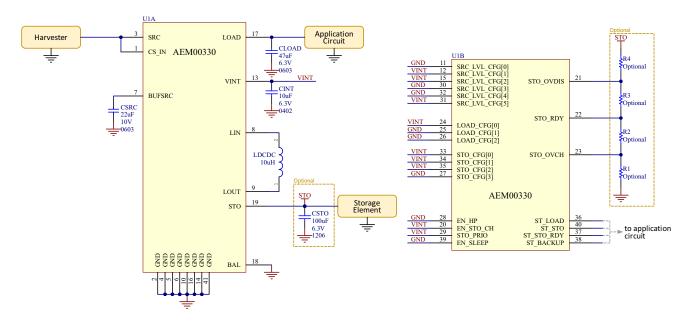


Figure 17: Schematic Example

Designator	Description	Quantity	Manufacturer	Link
U1	AEM00330 - Symbol QFN 40-pin	1	e-peas	order at sales@e-peas.com
L <sub>DCDC</sub>	Power inductor 10 μH - 1.76A	1	Murata	DFE252010F-100M
C <sub>LOAD</sub>	Ceramic Cap 47 μF, 6.3V, 20%, X5R 0603	1	Murata	GRM188R60J476ME15
C <sub>INT</sub>	Ceramic Cap 10 μF, 6.3V, 20%, X5R 0402	1	Murata	GRM155R60J106ME15
C <sub>SRC</sub>	Ceramic Cap 22 μF, 10V, 20%, X5R 0603	1	Murata	GRM188R61A226ME15D
C <sub>STO</sub> (optional)	Ceramic Cap 100 μF, 6.3V, 20%, X5R 1206	1	TDK	C3216X5R1A107M160AC

Table 11: Minimal Bill of Materials



# 13. Layout

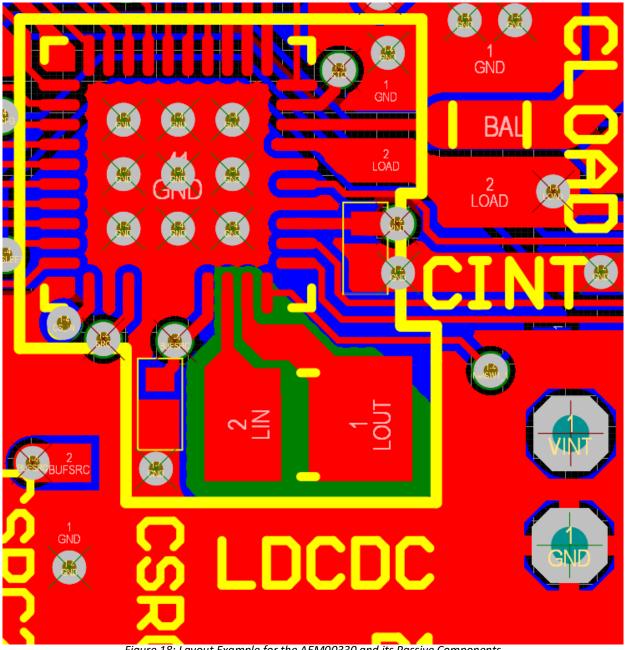


Figure 18: Layout Example for the AEM00330 and its Passive Components

NOTE: schematic, symbol and footprint for the e-peas component can be ordered by contacting e-peas support team at support@e-peas.com



# 14. Package Information

# 14.1. Plastic Quad Flatpack No-Lead (QFN 40-pin 5x5mm)

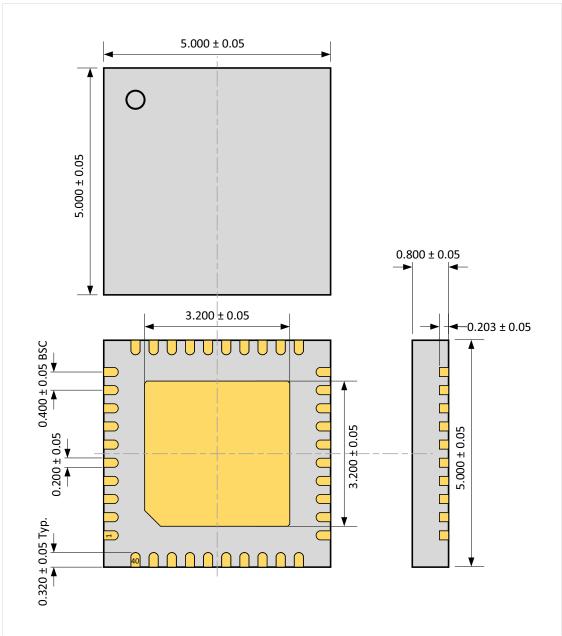


Figure 19: QFN 40-pin 5x5mm Drawing (All Dimensions in mm)



# 14.2. Board Layout

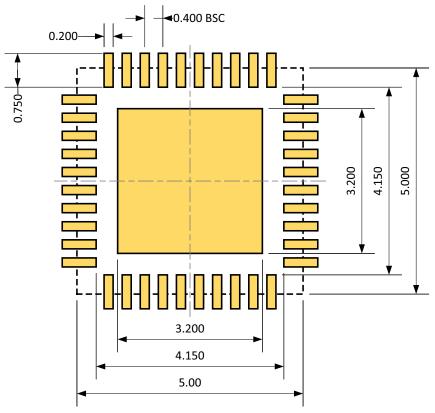


Figure 20: Recommended Board Layout for QFN40 package (All Dimensions in mm)



# **15. Revision History**

Revision	Date	Description
0.0	January, 2021	Creation of the document. Preliminary version.
1.0	June, 2021	First version of the document
1.1	August, 2021	Minor modifications
1.2	March, 2023	<ul> <li>Various aesthetic improvements.</li> <li>Explanations about BAL circuit.</li> <li>Section with precisions about the use of CS_IN.</li> <li>Removed LOAD_CFG[2] and related configurations.</li> <li>New "behavior" oscilloscope graphs with improved description.</li> <li>Moved various states description sections as sub-sections of a global section.</li> <li>Supply State description: explanation about SRC being set to high impedance when all nodes are fully charged.</li> <li>Updated "Typical use" of storage element vs STO_CFG[3:0] configuration.</li> <li>Replaced "asserted/de-asserted" by "HIGH/LOW".</li> <li>Changed CSRC from 15μF/0402 to 22μF/0603.</li> <li>Updated "Recommended Operation Conditions" with minimum capacitor values including derating and tolerances.</li> <li>Removed wong dimenson from package dimensions figure.</li> <li>Source in application example 1: replaced RF by PV cell.</li> </ul>

Table 12: Revision History